

Attorney Docket No.: NVID-P001125

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
Patent Application

Inventor(s): Schieck et al. Confirmation No.: 7655
Application No.: 10/789,637 Group Art Unit: ~~2822~~ 2822
Filed: February 27, 2004 Examiner: *K. DUONG*
Title: A FLIP CHIP SEMICONDUCTOR DIE INTERNAL SIGNAL ACCESS SYSTEM AND METHOD

Form 1449

U.S. Patent Documents

Examiner Initial	No.	Publ./Patent No.	Date	Patentee	Class	Sub-class	Filing Date
<i>KBP</i>	A	2001/0010356	8/2/01	Talbot et al.	250	307	2/10/01
	B	2001/0006233	7/5/01	Vallett	257	48	1/29/01
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	H						
	I						
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	K						

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
<i>KBP</i>	L	19515591	10/19/95	DE	H01L	23/525		x
	M							
	N							

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	R	
	S	
	T	
Examiner	<i>William D. Dwyer</i>	
	Date Considered	<i>4/15/2006</i>

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered.
Include copy of this form with next communication to applicant.